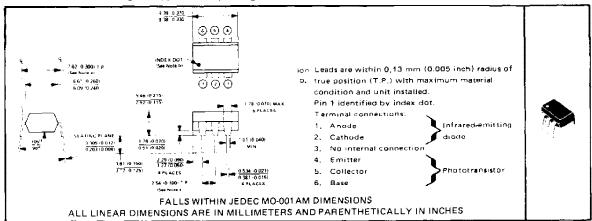
#### COMPATIBLE WITH STANDARD TTL INTEGRATED CIRCUITS

- Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N Phototransistor
- High Direct-Current Transfer Ratio
- High-Voltage Electrical Isolation . . . 5000-V Rating
- Plastic Dual-In-Line Package
- High-Speed Switching:  $t_r = 2 \mu s$ ,  $t_f = 2 \mu s$  Typical
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays, and Pulse Transformers

#### mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



## absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output Voltage±5 kV
Collector-Base Voltage
Collector-Emitter Voltage (See Note 1)
Emitter-Collector Voltage
Emitter-Base Voltage
Input-Diode Reverse Voltage
Input-Diode Continuous Forward Current
Continuous Power Dissipation at (or below) 25°C Free-Air Temperature:
Infrared-Emitting Diode (See Note 2)
Phototransistor (See Note 3)
Total, Infrared-Emitting Diode plus Phototransistor (See Note 4)
Storage Temperature Range
Lead Temperature 1,6 mm (1/16 inch) from Case for 10 Seconds

NOTES 1. This value applies when the base emitter diode is open-circuited

- 2. Denote linearly to 100°C free air temperature at the rate of 2 mW/°C.
- 3. Denate linearly to 100°C free-air temperature at the rate of 2 mW/ C.
- Derate linearly to 100°C free-air temperature at the rate of 3,33 mW/°C.

Texas Instruments

# TIL124, TIL125, TIL126 OPTOCOUPLERS

# electrical characteristics at 25°C free-air temperature

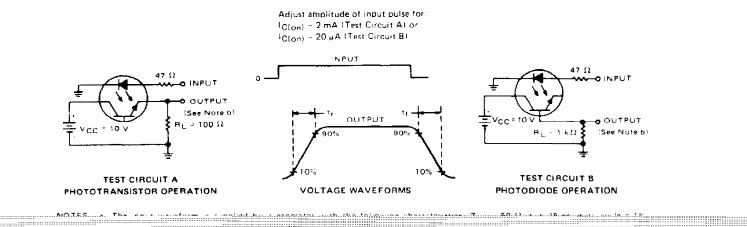
PARAMETER			TEST CONDITIONS	TIL124		TIL 125			TIL 126				
PARAMETER		MIN		TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
V(8R)C80	Collector-Base Breakdown Voltage		l <sub>C</sub> = 10 μA, l <sub>E</sub> = 0,	70			70			70			٧
VIBR)CEO	Collector-Emitter Breakdown Voltage		I <sub>C</sub> = 1 mA, I <sub>B</sub> = 0, I <sub>F</sub> = 0	30			30			30	-		٧
VIBR)EBO	Emitter-Base Breakdown Voltage		I <sub>E</sub> = 10 μA, I <sub>C</sub> = 0,	7			7			7			V
IR	Input Diode Static Reverse Current		VR = 3 V			10			10			10	дД
(C(on)	On-State Collector Current	Phototransistor Operation	VCE = 10 V, Ir = 10 mA.	1	3		2	5		5	9		mΑ
		Photodiode Operation	V <sub>CB</sub> = 10 V, I <sub>F</sub> = 10 mA, I <sub>E</sub> = 0	5	20		5	20		5	20		ДА
<sup>I</sup> C(off)	Off-State Collector Current	Oneration	V <sub>CE</sub> = 10 V, I <sub>F</sub> · 0 I <sub>B</sub> = 0		1	50		1	50		1	50	nA
		Photodiode Operation	V <sub>CB</sub> = 10 V, I <sub>F</sub> = 0, I <sub>E</sub> = 0		0.1	20		0.1	20		0.1	20	1
μŁΕ	Transistor Static Forward Current Transfer Ratio		VCE = 5 V, IC = 10 mA, ip = 0	50	100		100	200		100	550		
V <sub>F</sub>	Input Diode Static Forward Voltage		IF = 10 mA		1.2	1,4		1.2	1,4		1.2	1.4	v
VCE(sat)	Collector-Emitter Saturation Voltage		1 <sub>C</sub> = 1 mA, I <sub>F</sub> = 10 mA, I <sub>B</sub> = 0		0.25	0.4		0.25	0.4		0.25	0.4	٧
rio	Input-to-Output Internal Resistance		V <sub>in-out</sub> = 500 V, See Note 5	10''			10''			10			Ω
Cia	Input-to-Output Capacitance		V <sub>in-out</sub> = 0, f = 1 MHz, See Note 5		1	1.3		1	1.3		1	1.3	pF

NOTE 5: These parameters are measured between both input diode leads shorted together and all the phototransistor leads shorted together.

## switching characteristics at 25°C free-air temperature

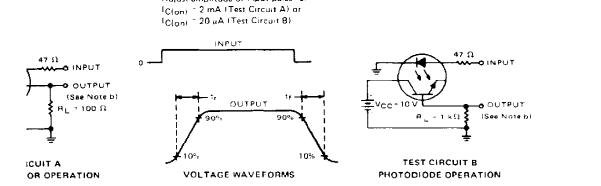
	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t,	Rise Time	Phototransistor	$V_{CC} = 10 \text{ V},  I_{C(on)} = 2 \text{ mA,R}_{L} = 100 \Omega,$		5	10	
tf	Falt Time	Operation	See Test Circuit A of Figure 1		5	10	цs
t <sub>r</sub>	Rise Time	Photodiode	$V_{CC} = 10 \text{ V}, I_{C(on)} = 20 \mu\text{A,R}_L = 1 \text{k}\Omega.$		1		
tf	Fall Time	Operation	See Test Circuit B of Figure 1		1		цs

#### PARAMETER MEASUREMENT INFORMATION



#### PARAMETER MEASUREMENT INFORMATION

Adjust amplitude of input pulse for



univaleum is cumplied by a sensition with the following characteristics 7 = 50.0 to 15 at identification 2.12



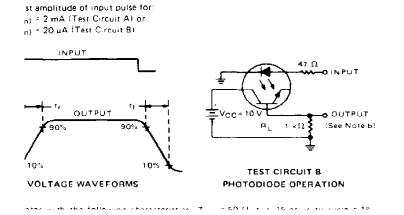
TEST CIR

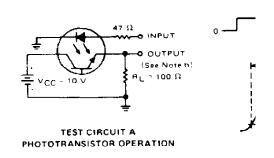
#### **I MEASUREMENT INFORMATION**

#### **PARAMETER**

Adju

IC(or



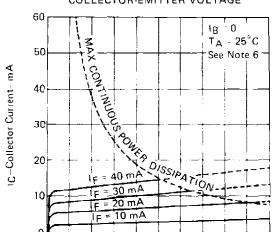


MOTEC . . The least management is supplied by a speed

## TYPICAL CHARACTERISTICS



# COLLECTOR CURRENT vs COLLECTOR-EMITTER VOLTAGE



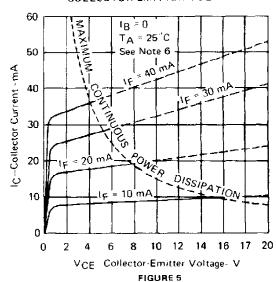
8

VCE~Collector-Emitter Voltage~V
FIGURE 3

10 12 14

# TIL126 COLLECTOR CURRENT

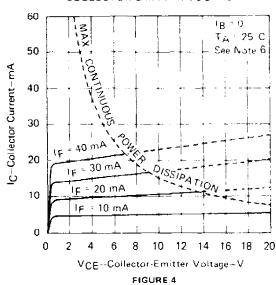
# COLLECTOR-EMITTER VOLTAGE



#### TIL 125

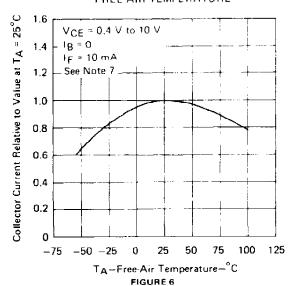
# COLLECTOR CURRENT vs





# RELATIVE ON-STATE COLLECTOR CURRENT

# FREE-AIR TEMPERATURE



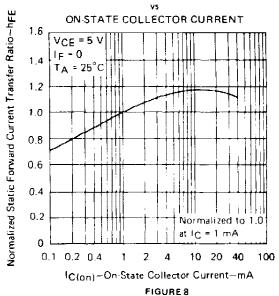
NOTES 6. Pulse operation of input diode is required for operation beyond limits shown by dotted lines.

7. These parameters were measured using pulse techniques,  $t_{\rm W}$  = 1 ms, duty cycle & 2%.

#### TYPICAL CHARACTERISTICS

#### OFF-STATE COLLECTOR CURRENT FREE-AIR TEMPERATURE 10 000 V<sub>CE</sub> = 10 V 4 000 Ψ÷ 1B = 0 IF = 0 1 000 IC(off)- Off State Collector Current 400 100 40 10 4 0.4 0.1 10 0 60 70 50 TA-Free-Air Temperature-°C

# NORMALIZED TRANSISTOR STATIC FORWARD CURRENT TRANSFER RATIO



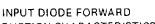
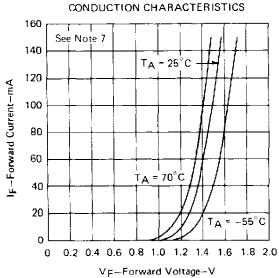


FIGURE 7



# COLLECTOR CURRENT

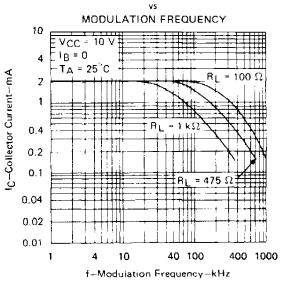


FIGURE 10

NOTE 7: These parameters were measured using pulse techniques,  $t_{\text{W}}\approx 1$  ms, duty cycle  $\lesssim 2\%$ 

FIGURE 9



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